

L Number	Hits	Search Text	DB	Tim stamp
1	2	5939312[pn]	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 17:33
2	2443	chamber near10 block near10 heat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 17:34
3	200415	printed near10 circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:09
4	42912	pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 17:35
5	21	(chamber near10 block near10 heat\$3) same ((printed near10 circuit) or pcr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 17:36
6	0	(chamber near10 block near10 heat\$3) same (printed near10 circuit) same pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 17:36
7	4	(chamber near10 block near10 heat\$3) same (printed near10 circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:02
8	59886	heat near2 sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:02
10	0	((heat near2 sink) same (chamber near10 block near10 heat\$3)) same pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:02
9	53	(heat near2 sink) same (chamber near10 block near10 heat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:03
11	0	(heat near2 sink) near10 pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:03
12	21	(heat near2 sink) same pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:03

13	0	(printed near10 circuit) same (heat near2 sink) same pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:08
14	3474	(printed near10 circuit) same (heat near2 sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:08
15	2110	(printed near10 circuit) near20 (heat near2 sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:08
16	0	((printed near10 circuit) near20 (heat near2 sink)) same thermocyl\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:08
17	0	((printed near10 circuit) near20 (heat near2 sink)) same pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:08
18	16	(printed near10 circuit) same pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:45
19	0	cover near10 rod near10 pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:45
21	31838	cover near10 pin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:45
22	0		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:46
23	0		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:46
24	4272		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:48
25	2001		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:48

26	59		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 18:49
27	5	evacuat\$3 same pcr same chamber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:01
28	128	polycarbonate near10 chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:02
29	0	(polycarbonate near10 chip) same pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:02
30	103	polycarbonate same pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:02
31	1	(polycarbonate same pcr) same chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:02
32	1	(polycarbonate same pcr) same circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:03
33	13	(polycarbonate same pcr) same chamber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:16
34	17060	durometer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:16
35	0	durometer same (chamber near10 block near10 heat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:16
37	0	(durometer same (printed near10 circuit)) same chamber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:16
36	72	durometer same (printed near10 circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:17

38	16	solder same (chamber near10 block near10 heat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:18
39	13667	solder near10 bumps	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:18
40	13667	solder near10 bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:18
41	0	(solder near10 bump) same (chamber near10 block near10 heat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:18
42	2	(solder near10 bump) same pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:22
43	246	microtiter near10 pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:22
44	0	(microtiter near10 pcr) same (printed near10 circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:22
45	0	(microtiter near10 pcr) same (chamber near10 block near10 heat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:22
46	4	(microtiter near10 pcr) same (heat near10 block)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:35
47	1172	independent near10 pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:35
48	289	(independent near10 pcr) near10 reaction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:35
49	1	((independent near10 pcr) near10 reaction) near10 chamber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:35

50	0	((independent near10 pcr) near10 reaction) same minatur\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:36
51	0	((independent near10 pcr) near10 reaction) same microfluid\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:36
52	14	independent\$3 near10 control near10 pcr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/22 19:43